

## United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandra, Vignus 22313-1450 www.uspto.gov

## \*BIBDATASHEET\*

Bib Data Sheet

**CONFIRMATION NO. 2684** 

| SERIAL NUMBER<br>10/663,967  | FILING OR 371(c)  | (        | <b>CLASS</b> 257                                | GRO                     | GROUP ART<br>2822  |                       |  | ATTORNEY<br>OOCKET NO.<br>5649-1161 |
|--|---|----------|---|-------------------------|--|-----------------------|--|-------------------------------------|
| APPLICANTS Hyun-Chul Kim, ** CONTINUING DATA   | Seould-City, KOREA, I   |          | LIC OF;   |                         |  |                       |  |                                     |
| IF REQUIRED, FOREI<br>** 12/10/2003  | (OREA 2002-68933 11   | /07/2002 | ED  |                         |  |                       |  |                                     |
| Foreign Priority claimed  35 USC 119 (a-d) conditions  yes no Met after with met  Verified and Acknowledged Examiner's Signature Initials  ADDRESS |   |          | STATE OR<br>COUNTRY<br>KOREA,<br>REPUBLIC<br>OF | SHEETS<br>DRAWING<br>15 |  | TOTAL<br>CLAIMS<br>25 |  | INDEPENDENT<br>CLAIMS<br>3          |
| 20792  TITLE  Methods of fabricating integrated circuit devices having fuse structures including buffer layers                                     |   |          |   |                         |  |                       |  |                                     |
| FILING FEE FEES:<br>RECEIVED No.   | Authority has been given in Paperto charge/credit DEPOSIT ACCOUNTfor following: |          |   |                         | ☐ All Fees ☐ 1.16 Fees (Filing) ☐ 1.17 Fees (Processing Ext. of time) ☐ 1.18 Fees (Issue) ☐ Other ☐ Credit |                       |  |                                     |